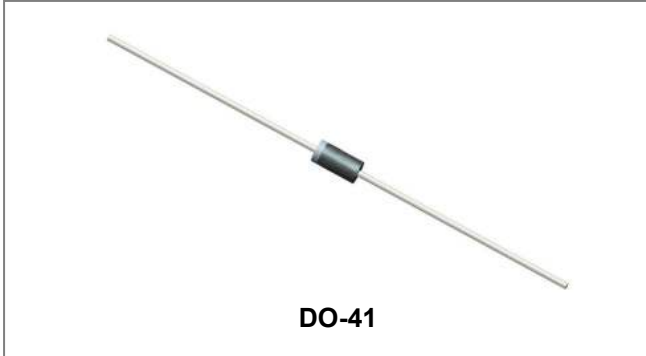


# FR101 THRU FR107

## FAST RECOVERY RECTIFIERS

Reverse Voltage - 50 to 1000 Volts Forward Current - 1.0 Ampere



### Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Fast switching for high efficiency
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed: 260 C/10 seconds, 0.375" (9.5mm) lead length, 5 lbs. (2.3kg) tension
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram



### Mechanical Data

- Case: JEDEC DO-41 molded plastic body
- Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.012 ounce, 0.33 grams

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	FR101	FR102	FR103	FR104	FR105	FR106	FR107	Units
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum average forward rectified current 0.375"(9.5mm) lead length at T <sub>A</sub> =75°C	I <sub>(AV)</sub>	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	30							A
Maximum instantaneous forward voltage at 1.0A	V <sub>F</sub>	1.3							V
Maximum DC reverse current T <sub>A</sub> =25 °C at rated DC blocking voltage T <sub>A</sub> =100 °C	I <sub>R</sub>	5.0 50.0							µA
Maximum Reverse Recovery Time (Note 1)	T <sub>rr</sub>	150				250	500		ns
Typical Junction Capacitance (Note 2)	C <sub>J</sub>	15.0							pF
Typical Thermal Resistance (Note 3)	R <sub>θJA</sub>	50.0							°C/W
Junction Temperature	T <sub>J</sub>	-65 to +150							°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150							°C

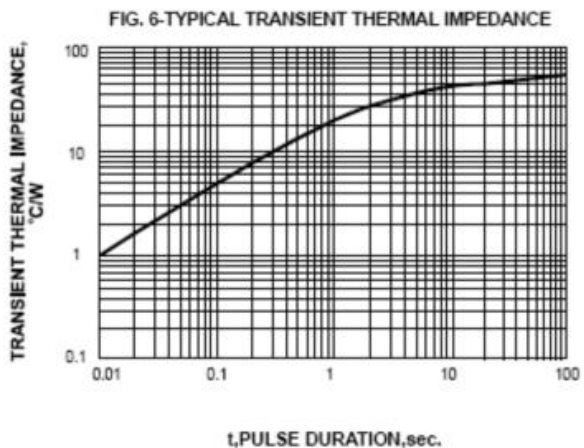
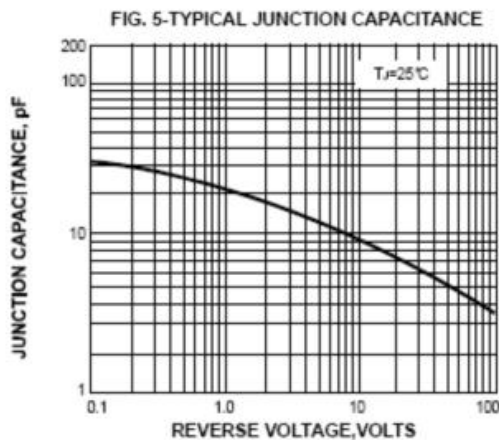
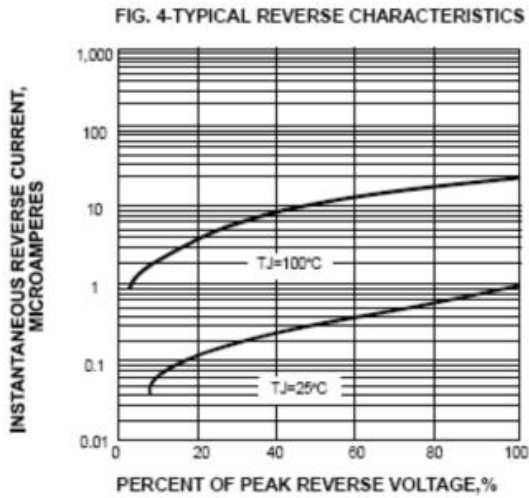
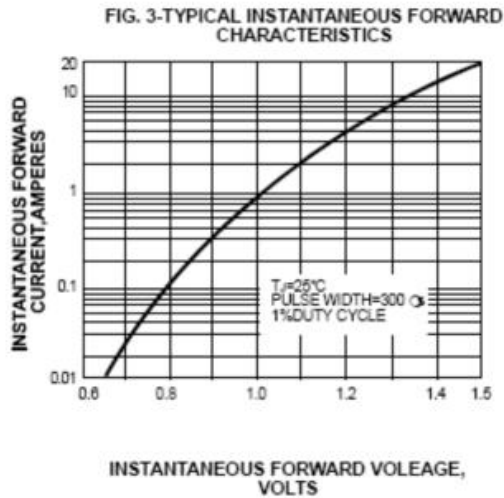
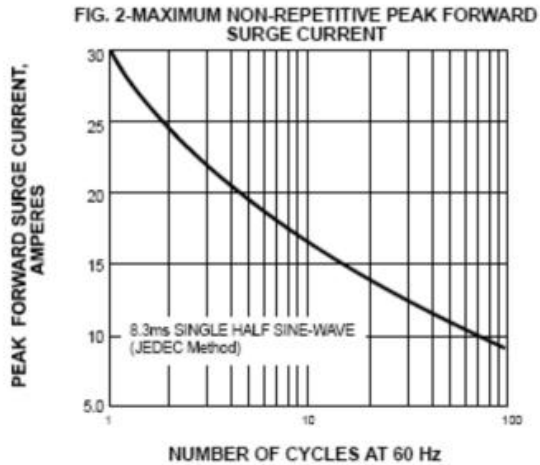
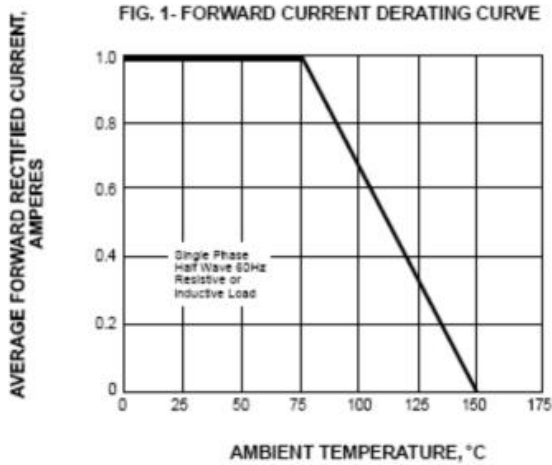
Note: 1. Reverse Recovery Test Conditions: IF=0.5A, IR=1.0A, IRR=0.25A

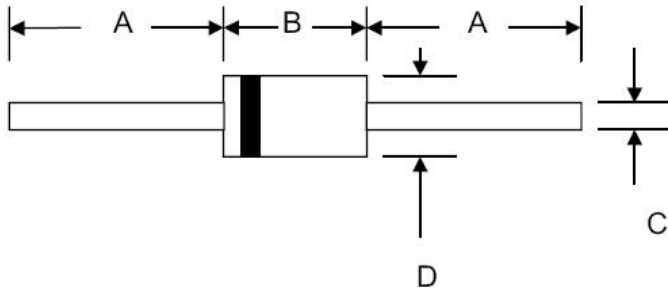
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

3. Thermal resistance from junction to ambient at 0.375"(9.5mm)lead length, P.C.B. mounted

- China - Germany - Korea - Singapore - United States •
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**Ratings and Characteristics Curves**



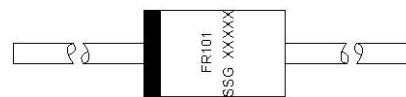
**Mechanical Dimensions DO-41**


SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	25.4	-	1.000	-
B	4.06	5.21	0.160	0.205
C	0.71	0.864	0.028	0.034
D	2.00	2.72	0.079	0.107

**Ordering Information**

Device	Suffix	Package	Shipping
FR101-FR107	TR	DO-41 (Pb-Free)	5000pcs / reel
FR101-FR107	TA	DO-41 (Pb-Free)	5000pcs / tape

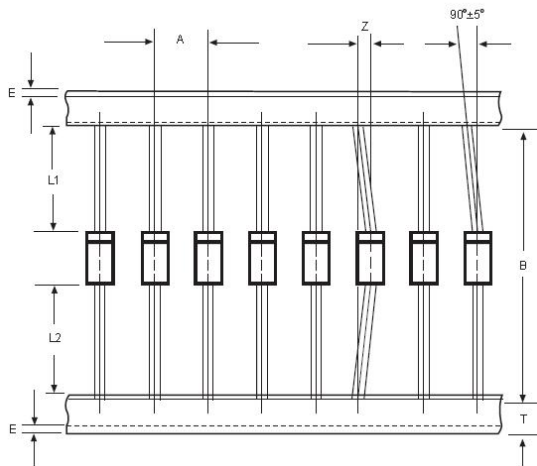
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**


Where XXXXX is YYWWL

FR101 = Part Name  
 SSG = SSG  
 YY = Year  
 WW = Week  
 L = Lot Number

Cautions: Molding resin  
 Epoxy resin UL:94V-0

**Carrier Tape Specification DO-41**


SYMBOL	Millimeters	
	Min.	Max.
A	4.50	5.50
B	50.9	53.9
Z	-	1.20
T	5.60	6.40
E	-	0.80
IL1-L2I	-	1.0



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